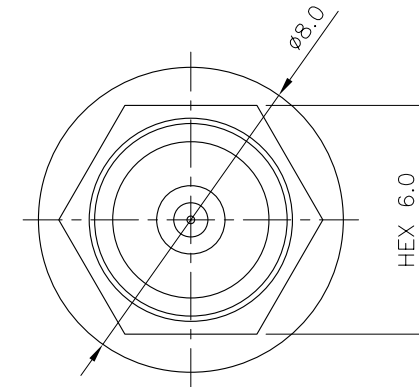
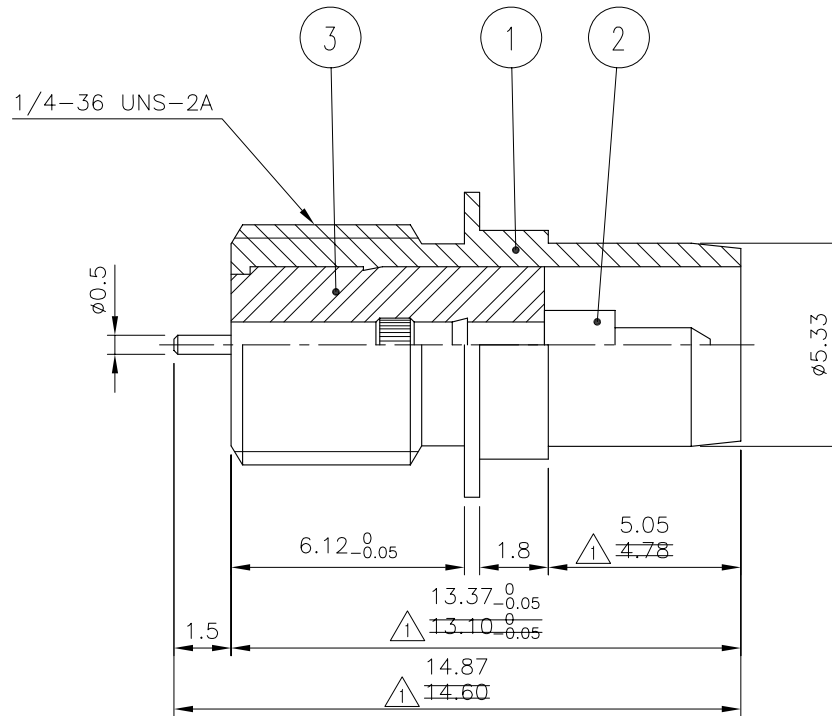


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	I.C.KIM	2013.08.22.
1	[설번No.201406-0007]업체요청(길이변경)	M.H.SONG	I.C.KIM	2014.06.16.



3	INSULATOR	1	TEFLON		DIN02185-N/1
2	CONTACT	1	MBsBD	Gold Plate (1.27μm)	DCT02849-5/1
1	BODY	1	SUS303	부동태 처리	DBD03341-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2013. 08. 22.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	E.H.KIM	KJ COMTECH CO.,LTD. TITLE BMA50 SOLDER END PB(F/F)
		DRAWN BY	I.C.KIM	
FINISH		SCALE	5/1	A4 DWG NO. CN03000-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	